

## **BZT52C15S**

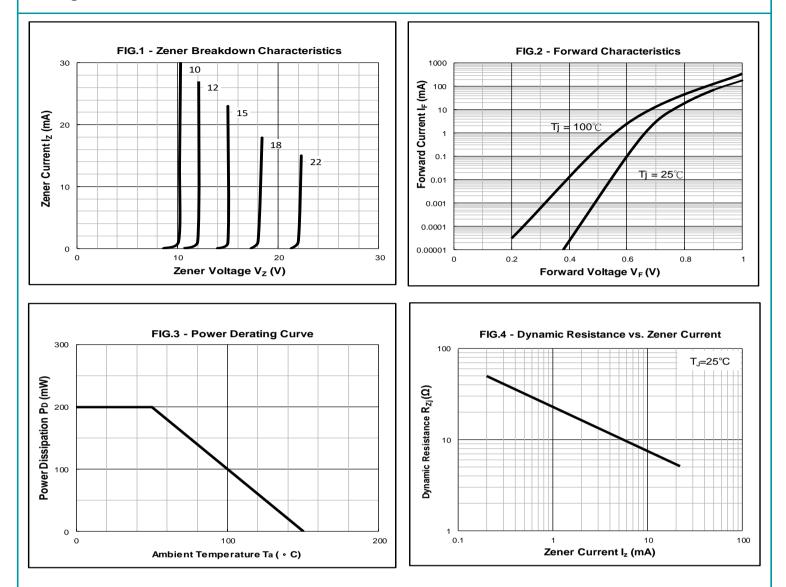
Surface Mount Zener Diode		Zener Voltage - 15V					
Description	Packag	e Outline	e				
Surface Device Type Mounting							
Low Zener Impedance							
<ul> <li>Power Dissipation of 200mW</li> </ul>							
<ul> <li>High Stability and High Reliability</li> </ul>		A		0.01	2000 T	) <i>(</i> ;	
Mechanical Data				501	D323 Top	View	
•Case: SOD323 Package							
•Case Material: "Green" Molding Compound UL Flammability Classification Rating 94V-0	Device	Device Schematic & PIN Configuration					
<ul> <li>Terminals:Matte tin plated,solderable per MIL-STD-750 ,method 2026</li> </ul>					1		
<ul> <li>Component in accordance to RoHS</li> </ul>							
Halogen Free							
Note: Products with logo HV or Hy		I			1		
are made by HY Electronic (Cayman) Limited.							
	Produc	Product Type Marking Code					
Ordering Information			•				
Package :SOD323		_					
Reel Size :7 (inches)				<b>/</b> I			
Quantity Per Reel :3,000/Tape & Reel			v	V J	$\square$		
Quantity One Box :45,000/Tape & Reel					4		
Maximum Ratings (@TA = +25°C, unless otherwise s	pecified.)						
Absolute Ratings	· · ·						
Parameter	Symbol		Value				Unit
Forward Voltage @ IF = 10mA	Vf		0.9 (1)				V
Power Dissipation	Po				mW		
Storage Temperature Range	Тѕтс	Tsrg -65 to +150		° C			
Electrical Characteristics							
Parameter	Test Conditi	ons S	ymbol	Min	Тур	Max	Unit
Zener Voltage Range	Vz@lzt		Vz	13.8	15	15.6	V
Zener Impedance	Zzt@lzt		Zzt	-	-	30	Ω
Zener Impedance	Zzk@lzk		Zzk	-	-	200	Ω
Reverse Leakage Current	IR@VR		IR	-	-	0.1	uA
Typical Temperature Coefficent	Tc@lztc		Iztc	9.2	-	13	mV/ ∘ C
Note:1. Short duration test pulse used to minimize self-heating	effect						
2. Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0		areas 25mr	n²				
				D	7750041	59 7 00 4	01-BC1589
				D2			J1-BC150

Rev-0, 14-Oct-2022



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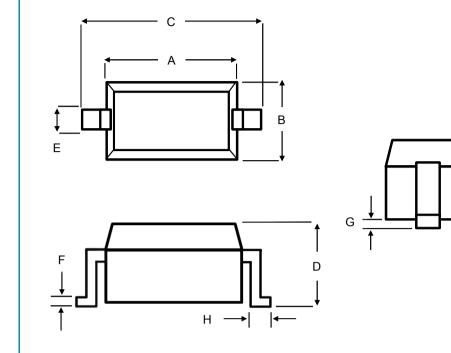
#### **Rating and Characteristic Curves**





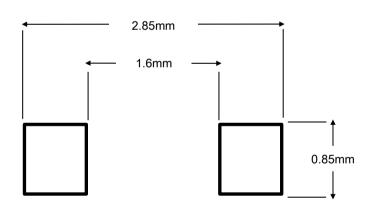
## **BZT52C15S**

### Package Outline Dimensions



SOD323 Package					
Dim	Min	Max			
А	1.60	1.80			
В	1.20	1.40			
С	2.50	2.70			
D	-	1.00			
Е	0.25	0.35			
F	0.08	0.15			
G	-	0.10			
Н	0.25	0.40			
All Dimensions in mm					

#### Suggested Soldering Pad Layout



Note:

1. The pad layout is for reference purposes only.

2.General tolerance ±0.05mm

#### Disclaimer

All specifications and data are subject to be changed without notice to improve reliability function or design or other reasons.

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